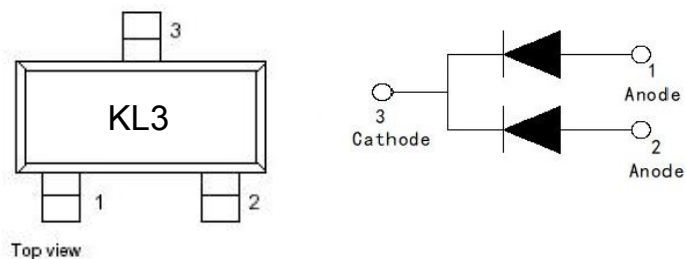


一、Features 产品特性



MAXIMUM RATINGS($T_a=25^\circ\text{C}$) 最大额定值

CHARACTERISTIC 特性参数	Symbol 符号	Rating 额定值	Unit 单位
Reverse Voltage 反向电压	V_R	30	Vdc
Peak Forward Current 正向峰值电流	I_F	200	mAdc

THERMAL CHARACTERISTICS 热特性

CHARACTERISTIC 特性参数	Symbol 符号	Max 最大值	Unit 单位
Total Device Dissipation FR-5 Board(1) $T_A=25^\circ\text{C}$	P_D	225	mW
Total Device Dissipation Alumina Substrate,(2) $T_A=25^\circ\text{C}$ 总耗散功率 氧化铝衬底	P_D	300	mW
Junction and Storage Temperature结温和储存温度	T_J , T_{stg}	150, -55 ~ 150	$^\circ\text{C}$

1. FR-5=1.0×0.75×0.062in, printed-circuit board.

2. Alumina=0.4×0.3×0.024in, 99.5%alumina

ELECTRICAL CHARACTERISTICS 电特性

($T_A=25^{\circ}\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Test Condition 测试条件	Min 最小值	Type 典型值	Max 最大值	Unit 单位
Reverse Voltage Leakage Current 反向漏电流	I_R	$V_R=25\text{Vdc}$	—	—	1.0	μA
Reverse Breakdown Voltage 反向击穿电压	$V_{(BR)}$	$I_{BR}=10\mu\text{Adc}$	30	—	—	Vdc
Forward Voltage 正向电压	V_F	$I_F=0.1\text{mAdc}$	—	—	240	mV
		$I_F=1.0\text{mAdc}$	—	—	320	
		$I_F=10\text{mAdc}$	—	—	400	
		$I_F=30\text{mAdc}$	—	—	500	
		$I_F=100\text{mAdc}$	—	—	1000	
Total Capacitance 电 容	C_T	$V_R=1\text{V}, f=1.0\text{MHz}$	—	—	10	pF
Reverse Recovery Time 反向恢复时间	t_{rr}	$I_F=I_R=10\text{mAdc},$ $R_L=100\Omega$		—	5.0	ns

Typical Performance Characteristics

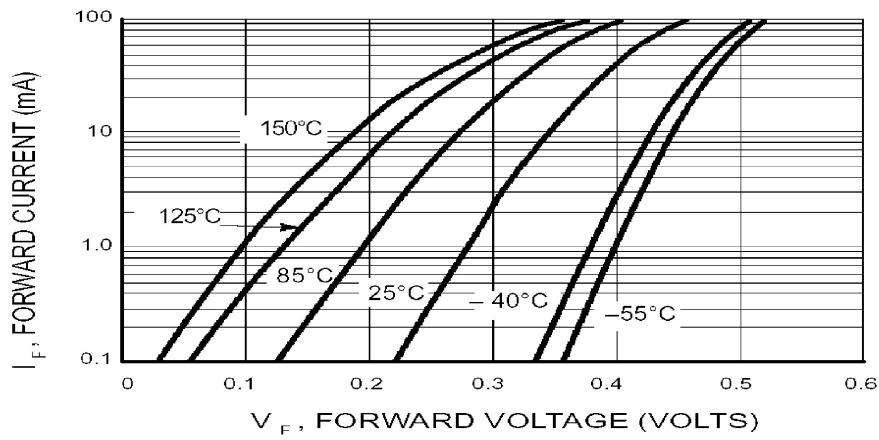


Fig.1 I_F — V_F

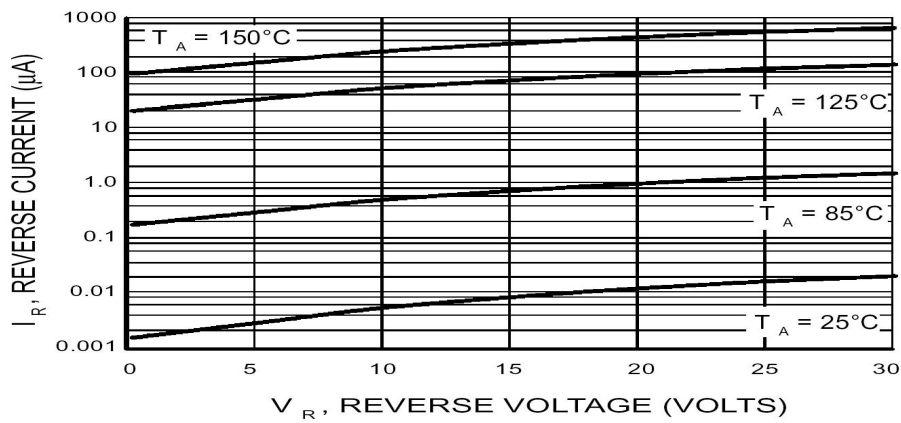


Fig.2 I_R — V_R

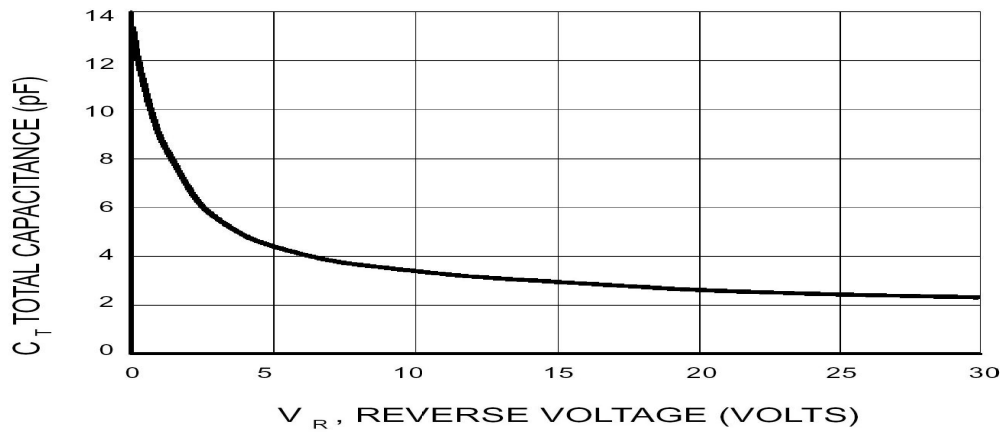
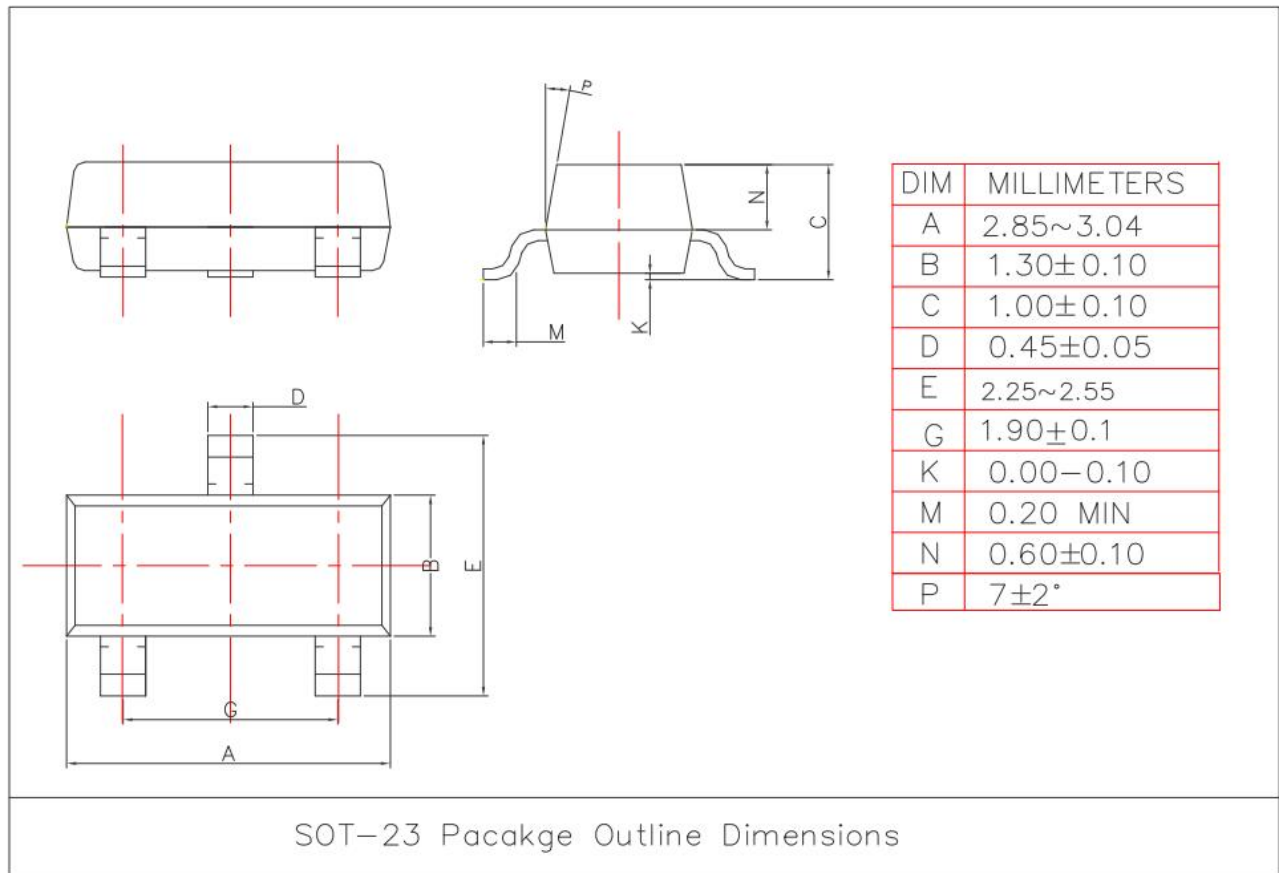
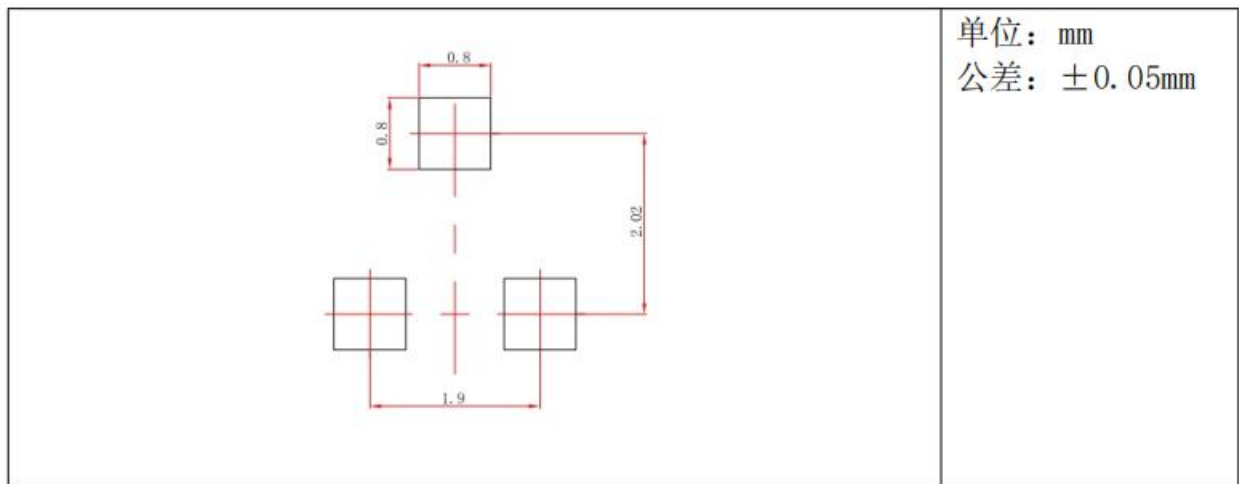


Fig.3 C_T — V_R

二、SOT-23 外形尺寸 (SOT-23 DIMENSION)

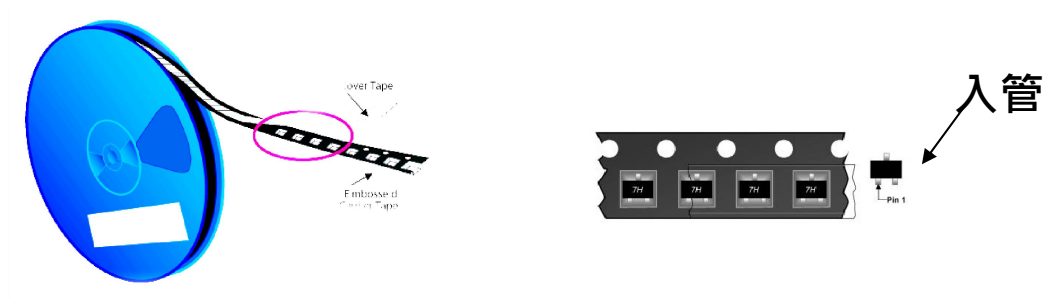


三、焊盘尺寸设计 SOT-23 Suggested Layout

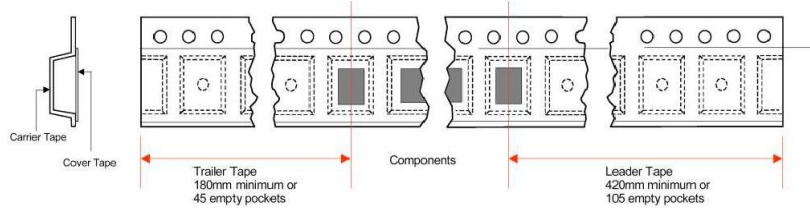


四、包装方式Packings

封装形式	卷盘尺寸	只/卷	内盒尺寸	卷盘/内盒	只/内盒	外箱尺寸	内盒/外箱	只/外箱
SOT-23	7"	3000	190X190X135 mm	10	30000	430 X 400 X 215 mm	6	180K
			203X203X195 mm	15	45000	440 X 440 X 230 mm	4	180K



SOT-23 产品编带、包装图



SOT-23 带尾、带头空封数

